

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
Nozomu Takano		12/25/2007
Masaki Kamiya		12/26/2007
RECEIVING PARTY DATA		
Name:	Hitachi Chemical Company, Ltd.	
Street Address:	1-1, Nishi-Shinjuku 2-chome, Shinjuku-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	163-0449	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	11912934	
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Total Attachments: 1		
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PATENT
REEL: 022225 FRAME: 0112

ASSIGNMENT

Whereas, I/we,

NameAddress1) **Nozomu TAKANO**

c/o Electronic Materials R&D Center, HITACHI CHEMICAL COMPANY, LTD.,

1500, Ogawa,
Chikusei-shi, Ibaraki 308-8521 Japan

c/o Shimodate Works, HITACHI CHEMICAL COMPANY, LTD.,

2) **Masaki KAMIYA**1500, Ogawa,
Chikusei-shi, Ibaraki 308-8521 Japan

hereinafter called assignor(s), have invented certain improvements in

COMPOSITE, PREPREG, LAMINATED PLATE CLAD WITH METAL FOIL, MATERIAL FOR CONNECTING CIRCUIT BOARD, AND MULTILAYER PRINTED WIRING BOARD AND METHOD FOR MANUFACTURE THEREOF

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on **October 29, 2007**, Serial No. **11/912934**; and

Whereas

HITACHI CHEMICAL COMPANY, LTD.1-1, Nishi-Shinjuku 2-chome,
Shinjuku-ku, Tokyo 163-0449 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

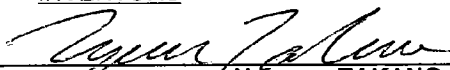
NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

INVENTORSDATE SIGNED

1):

Name:


Nozomu TAKANO

25/12/2007

2):

Name:


Masaki KAMIYA

26/12/2007